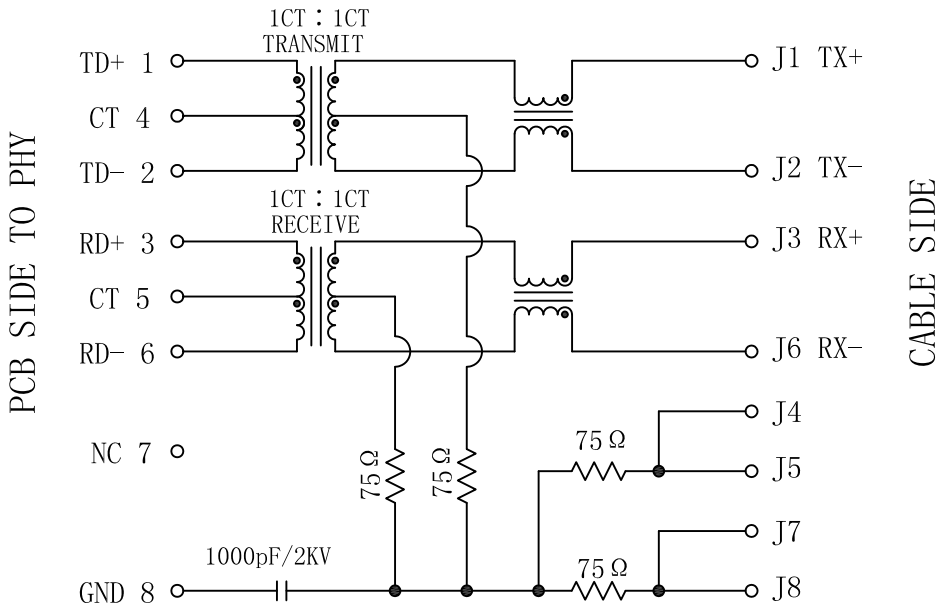
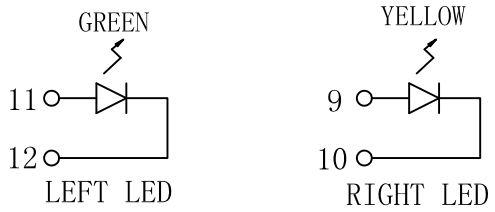
Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2011/01/24	



ELECTRICAL SPECFICATIONS @25℃

1. Turn Ratio(±2%):
   TX=1CT：1CT RX=1CT：1CT
2. Inductance OCL: 350uH MIN
   @100KHz, 0.1V, 8mA DC Bias
3. Insertion Loss:
   -1.1dB MAX @ 0.1～100MHz
4. Return Loss:
   -18dB MIN @ 0.5～30MHz
   -15.5dB MIN @ 40MHz
   -13.6dB MIN @ 50MHz
   -12dB MIN @ 60～80MHz
5. Cross talk:
   -40dB TYP @ 0.1～100MHz
6. Common Mode Rejection:
   -50dB TYP @ 0.1～30MHz
   -40dB TYP @ 30～60MHz
   -35dB TYP @ 60～100MHz
7. Hipot Test: 1500Vrms MIN
8. Operating Temperature: 0℃～70℃.

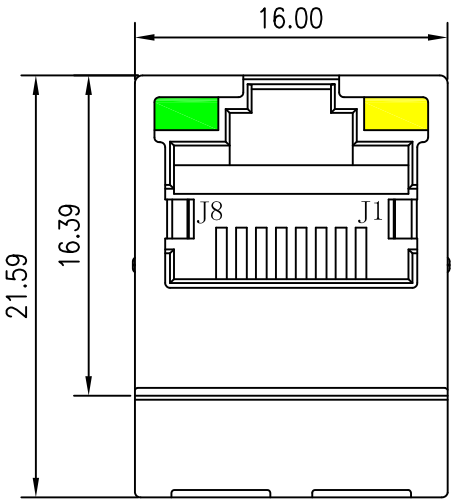


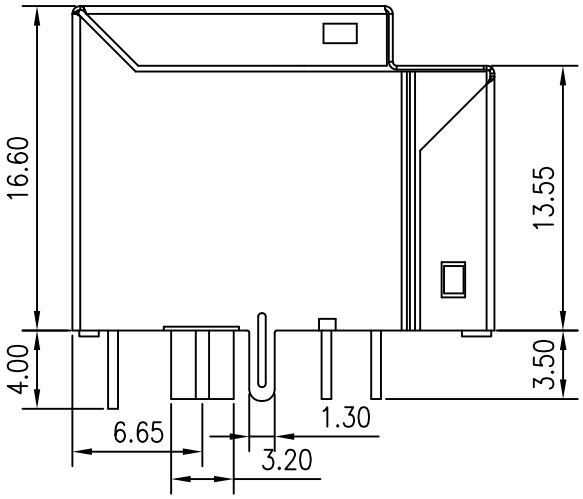
Emitting Color	λp(nm)	VF@IF=20mA	IR @VR=5V
GREEN	565	1.8~2.6V	10μA max
YELLOW	585	1.8~2.6V	10μA max

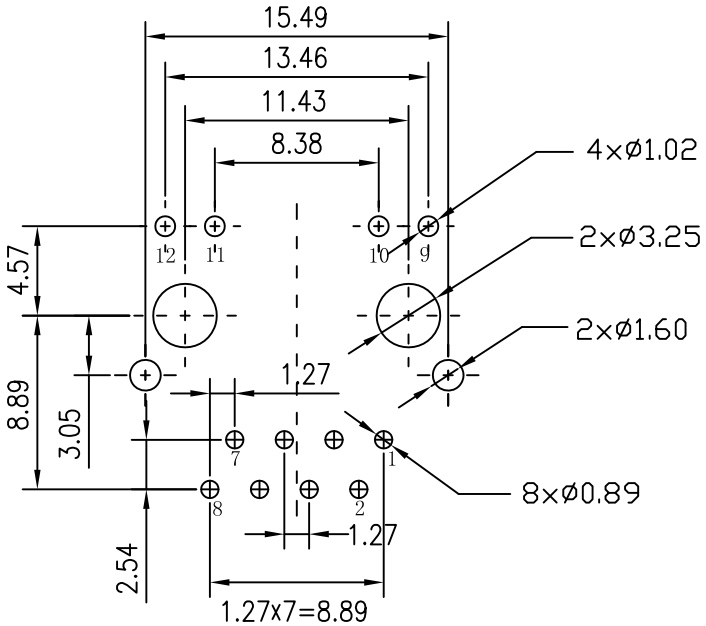
X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX ±0.25	CHKD:	Title: Vertical RJ45 Connector With 10/100 Magnetic	
X:XXX ±0.05	DR: TOM		
ANGLES ±1°	UNIT: mm	PART NO.: LPJD1011BENL	
SCALE: 2/1	SHEET: 1/2	REV: A	LP11012408

Mechanical:

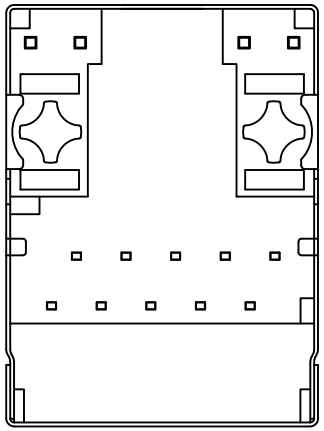
REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2011/08/12	

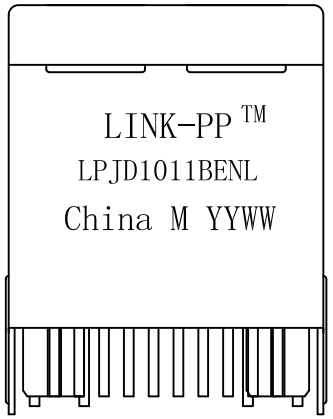






SUGGESTED PCB LAYOUT (TOP VIEW)





NOTES:

1. Designed to support application, such as SOHO(ADSL modems), LAN-on Motherboard(LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
   Housing Material:Thermoplastic PBT+30%G.F UL94V-0
   Contact Material:Phosphor Bonze C5210R-EH Thickness=0.35mm
   Pins:Brass C2680R-H Thickness=0.35mm
   Shield:Copper alloy Brass H65Y Thickness=0.2mm
   Contact plating: Gold 6 micro-inches Min. In contact area.
4. Wave solder tip temperature: 265℃ Max, 5 Sec Max

X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX ±0.25	CHKD:	TITLE: Vertical RJ45 Connector With 10/100 Magnetic	
X:XXX ±0.05	DR: C.H.Y		
ANGLES ±1°	UNIT: mm	PART NO.: LPJD1011BENL	
SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO.: LP11012408